

**AMENDMENT**

In response to the Office Action dated 25 November  
2005. Please amend the above-identified patent application  
5 as follows:

**In the specifications**

(1) Please insert the following sentence at the beginning  
of line 14 of page 1: "which is incorporated by reference in  
10 its entirety,"

(2) Please amend line 8 of page 45 to read: "the sacrificial  
layer. It is ~~totally~~ removed from within"

15 **In the claims**

Please amend the claims as follows:

20 1. (Currently amended)

A method of manufacturing a plurality of micro  
enclosures on a substrate wafer, comprising steps of: